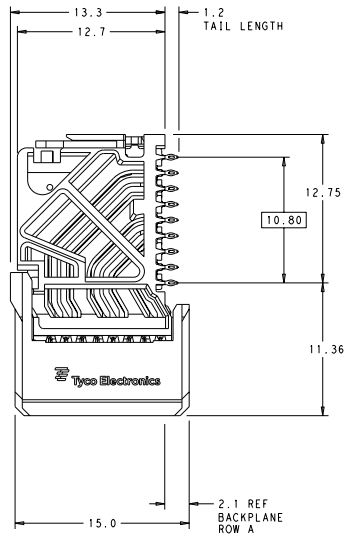
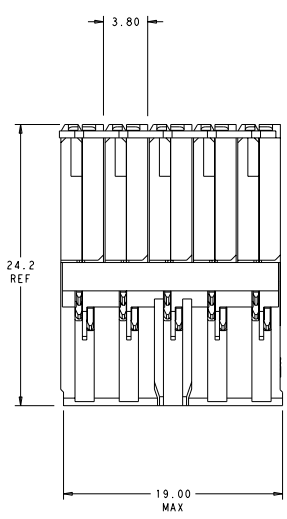
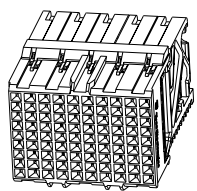


8	7	6	5	4	3	2	1
DATE REVISION TO IMPLEMENTED	REVISION FOR FABRICATION						
00	01						
ALL RIGHTS RESERVED							

REV	DATE	DESCRIPTION	BY	CHK	APP
00					
01		REVISED PER ECO-12-000417			

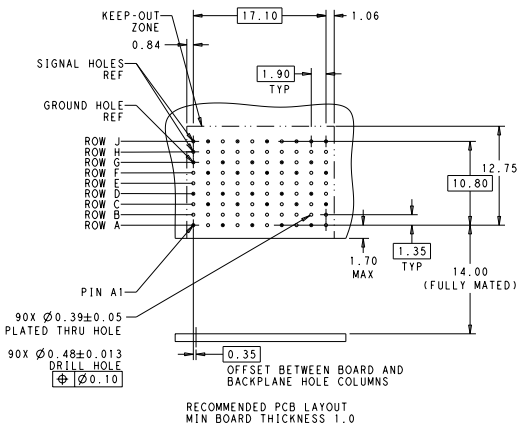
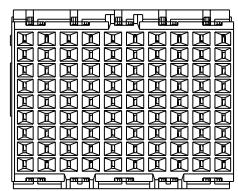


- ⚠ MATERIAL:  
HOUSING: LCP, GLASS FILLED, UL94V-0.  
TERMINALS: HIGH PERFORMANCE COPPER ALLOY.
- ⚠ FINISH:  
30μ" SELECTIVE GOLD IN CONTACT AREA. SELECTIVE TIN ON PCB TAILS, NICKEL OVERALL.
- ⚠ FINISH:  
30μ" SELECTIVE GOLD IN CONTACT AREA. SELECTIVE TIN-LEAD ON PCB TAILS, NICKEL OVERALL.



SCALE 4:1

REFER TO WWW.TE.COM FOR PRODUCT AVAILABILITY



RECOMMENDED PCB LAYOUT  
MIN BOARD THICKNESS 1.0

NONE	⚠	2007705-5
NONE	⚠	2007705-1
KEY POSITION	FINISH	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		REV	10FEB2011	REV	10FEB2011	REV	10FEB2011	REV	10FEB2011
DATE	02/10/2011	BY	SL/08	DATE	02/10/2011	BY	SL/08	DATE	02/10/2011
DESIGNED	SL/08	CHECKED	SL/08	DESIGNED	SL/08	CHECKED	SL/08	DESIGNED	SL/08
DRAWN	SL/08	APPROVED	SL/08	DRAWN	SL/08	APPROVED	SL/08	DRAWN	SL/08
DATE	02/10/2011	DATE	02/10/2011	DATE	02/10/2011	DATE	02/10/2011	DATE	02/10/2011
SCALE	4:1	SCALE	4:1	SCALE	4:1	SCALE	4:1	SCALE	4:1
CUSTOMER DRAWING		CUSTOMER DRAWING		CUSTOMER DRAWING		CUSTOMER DRAWING		CUSTOMER DRAWING	

**TE** TE Connectivity  
IMPACT, 3 PAIR, DAUGHTERCARD  
10 COLUMN, UNGUIDED SIGNAL  
MODULE, 0.395 EVELT